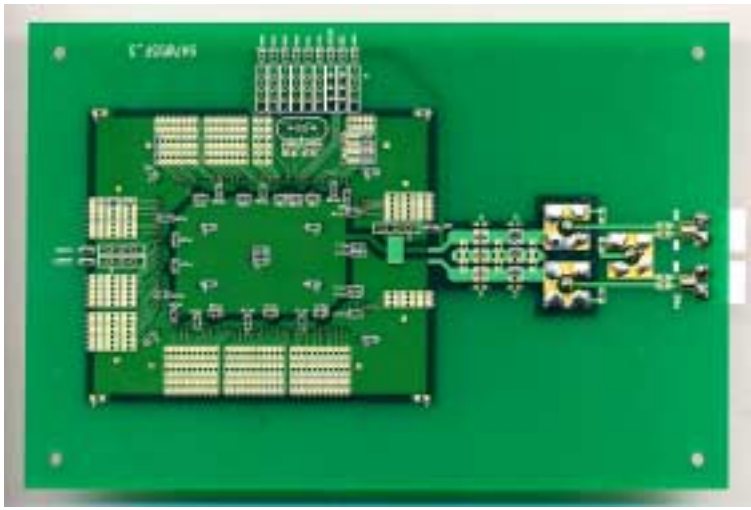
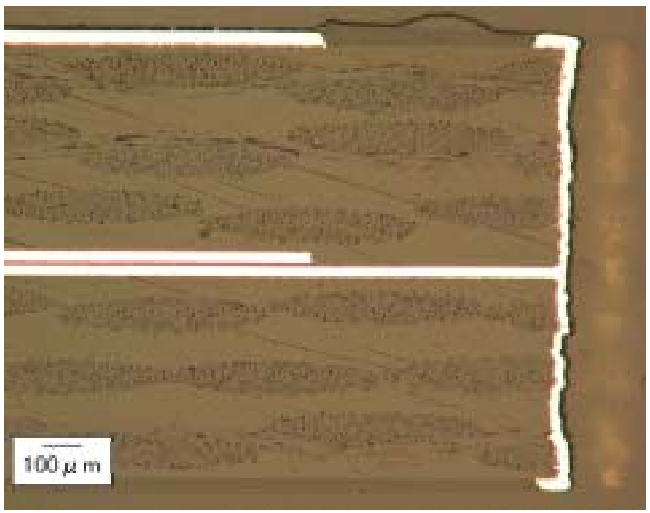
PWB Examples 1

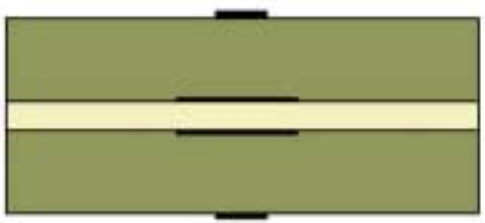
4 Layer Board





} FARADFLEX BC12

4 LAYER BOARD



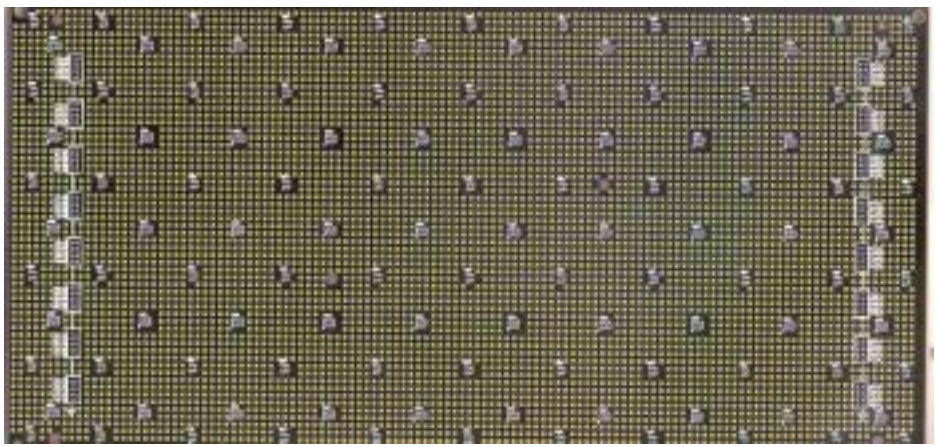
L1

L2
L3 } FARADFLEX CORE

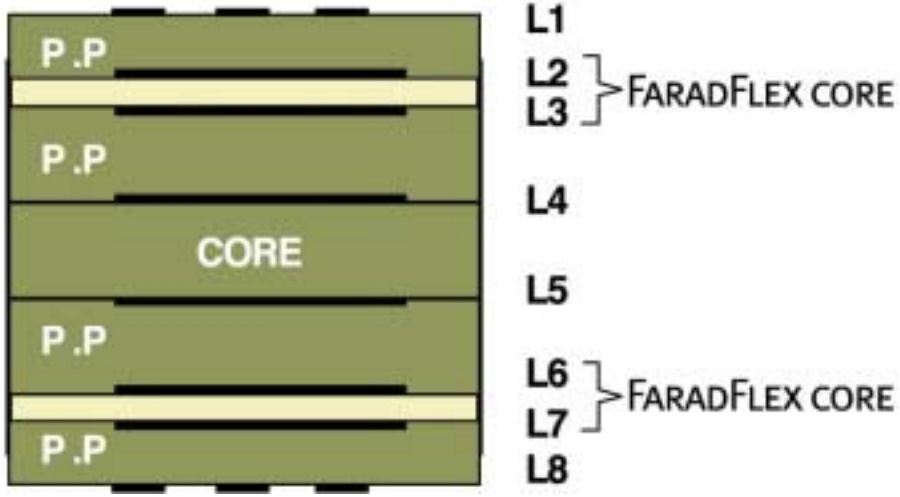
L4

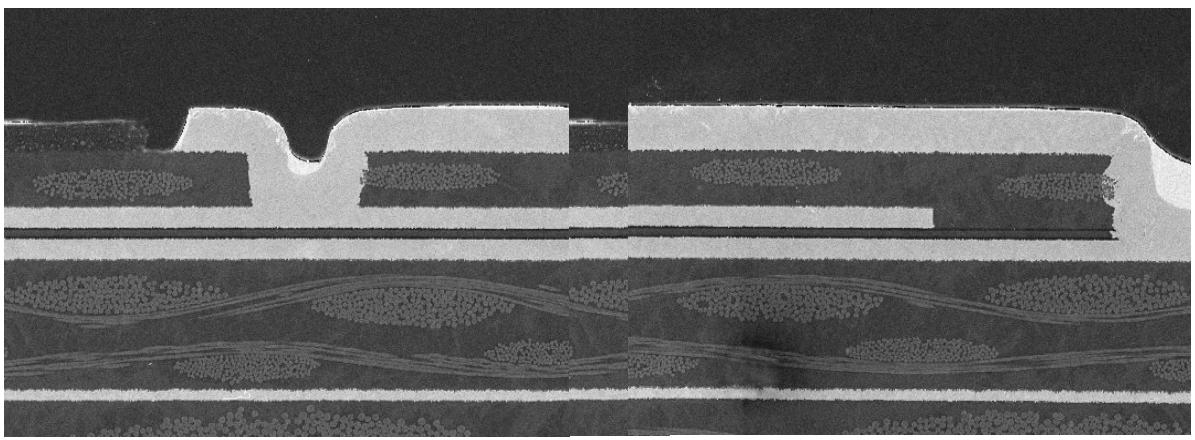
PWB Examples 2

8 Layer Board



8 LAYER BOARD with MICRO-VIA



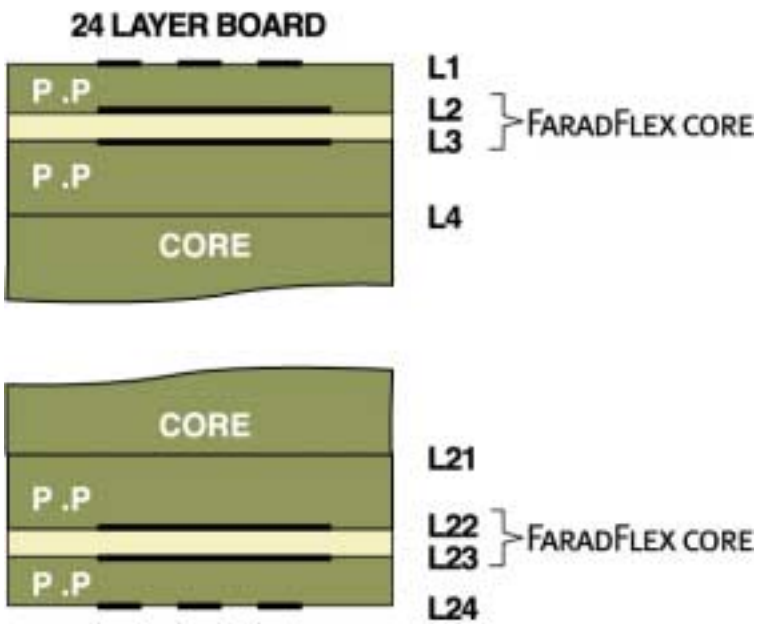


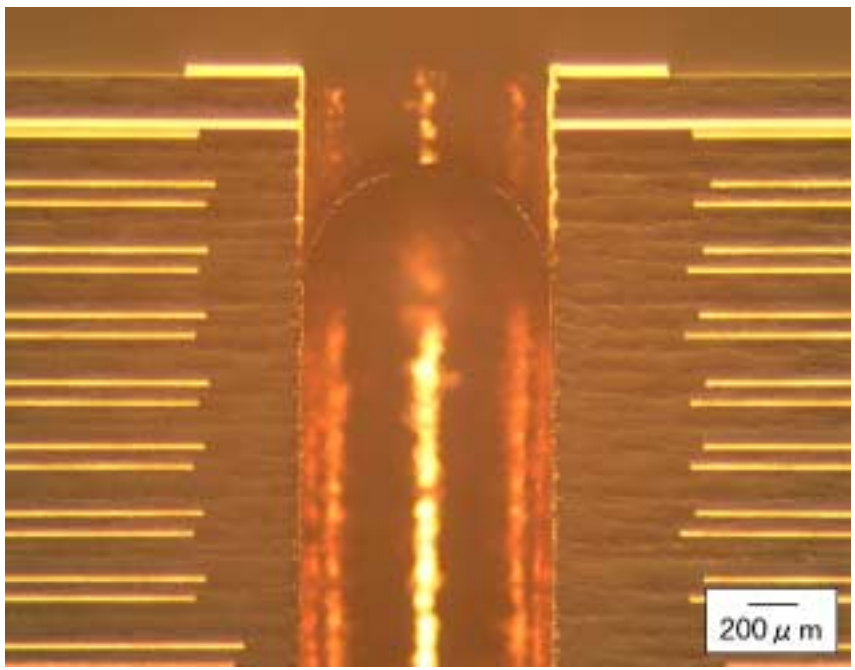
FARADFLEX
BC12

OAK-MITSUI TECHNOLOGIES
MITSUI KINZOKU CORPORATE GROUP

PWB Examples 3

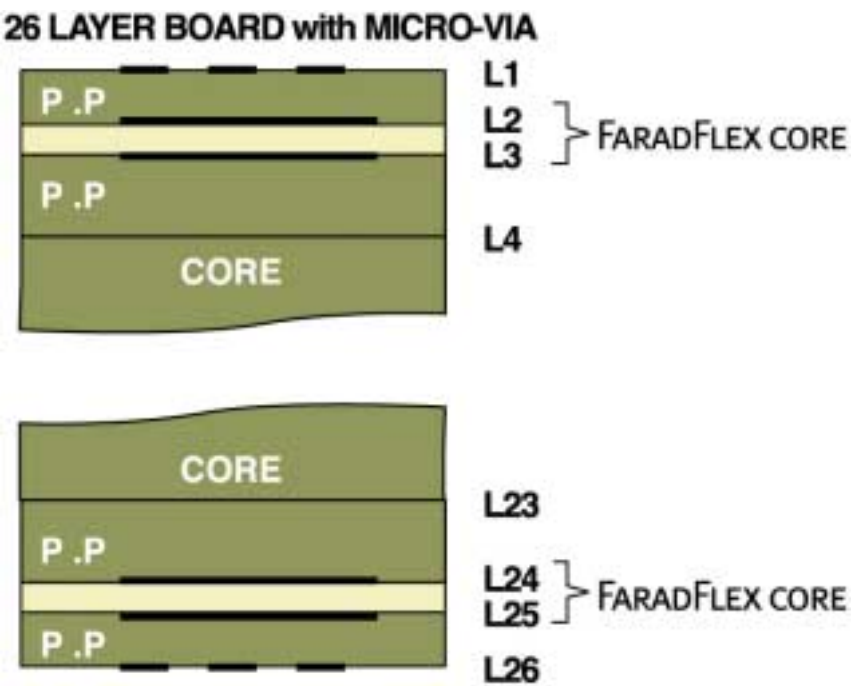
24 Layer Board



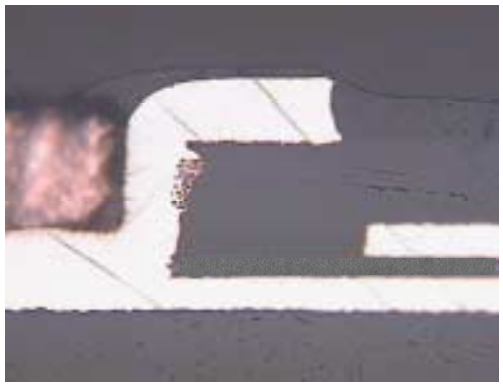


FARADFLEX
BC12

PWB Examples 4



Micro-via Plating



FARADFLEX BC24

Thermal Solder Shock 288C x6



FARADFLEX BC12

Reliability test

- Dielectric Withstanding Voltage : 500V Passed, No failure
- T-260 Time to Delamination : *BC12* 6.3min, *BC24* 5.2min
- Blind Via Plating Defects : No defects found
- Thermal Solder Shock – 6x : No defects found
- Liquid-Liquid : *BC24* 4.2%(500cycle)